TOSHIBA

ST1200FXF21

NEW PRODUCT GUIDE

Outline

As the successor to the 2500-V, 1000-A insulated-gate bipolar transistor (IGBT), Toshiba are marketing their newly developed 3300-V, 1200-A IGBT, which comes in a flat package with compression-bonded encapsulation.

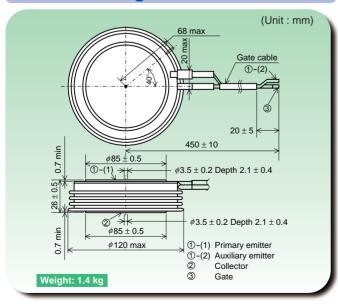
The new IGBT uses Toshiba's original multi-pellet alloy-free assembly structure. The bonding wires and soldering used in conventional plastic-module IGBTs have been dispensed with. As a result, the new product offers improved longevity and high reliability during thermal cycling.

Applications include high-voltage DC transmission equipment, static VAR compensators, and inverters for driving the motors of electric trains.

Features

- All electrical terminals and connections use compression-contact encapsulation. As a result, the IGBT is much less prone to damage caused by the junctions between the external terminals' leads and the internal semiconductor device getting hot and breaking. In this regard the IGBT is now as reliable as a GTO thyristor with the same structure.
- If the new IGBT is electrically damaged and breaks down, current flows directly between the collector and the emitter. In particular, when components are connected in series, there is no residual high voltage remaining from the snubber circuit or any other circuits connected to the product, and thus electrical stability is maintained. In addition, since the breakdown short circuit ensures that the device remains on, this IGBT is particularly effective in designs consisting of multiple components connected in series where built-in redundancy is required. Furthermore, even if, for example, the IGBT is damaged by surge current, its internal structural materials will not rupture the package and scatter.
- Because the IGBT uses a hermetically sealed structure with ceramic and copper terminals to seal in the inert gases, the IGBT is highly resistant to humidity and other climatic factors. In addition, the new IGBT's characteristics remain unaffected by pulse power because the thermal resistance over a brief period (the transient thermal resistance) of the IGBT is smaller than that of plastic module IGBTs with the same ratings. This is achieved by the thermal capacity of the metal terminals that come into direct contact with the semiconductor chip.

Package Dimensions





Technical specification

■ Maximum Ratings

Characteristic		Symbol	Rating	Unit	
Collector-emitter voltage		V _{CES}	3300	V	
Gate-emitter voltage		V _{GES}	± 20	V	
Collector current	DC	Ic	1200	А	
	1 ms	I _{CP}	2400	А	
Forward current	DC	lF	1200	А	
	1 ms	I _{FM}	2400	А	
Collector power dissipation (Tc = 25°C)		Pc	7100	W	
Junction temperature		Tj	-20~125	°C	
Storage temperature		T _{stg}	-40~125	°C	
Mounting force		_	31.5 ± 3.2	kN	

■Electrical characteristics

(T_C=125°C (except R_{th}))

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Characteristic		Symbol	Test conditions	Min	Тур.	Max	Unit
Collector cut-off current		ICES	V _{CE} = 3300 V,V _{GE} = 0 V	-	_	300	mA
Gate-emitter cut-off voltage		V _{GE(off)}	$V_{CE} = 5 \text{ V,I}_{C} = 1.2 \text{ A}$	_	3.8		V
Collector-emitter saturation voltage		V _{CE(sat)}	$I_C = 1200 \text{ A}, V_{GE} = 15 \text{ V}$	-	5.5	_	V
Input capacitance		Cies	$V_{CE} = 10 \text{ V}, V_{GE} = 0 \text{ V},$ f = 1 MHz	-	220	-	nF
Switching time	Rise time	tr	Inductive load V _{CC} = 1500 V, I _C = 1200 A, V _{GG} = \pm 15 V, R _{G(on)} = 10 Ω , R _{G(off)} = 3.3 Ω	-	-	-	μs
	Turn-on time	ton		-	_	_	μs
	Fall time	t _f		-	1.5	_	μs
	Turn-off time	toff		-	2.7	_	μs
Forward voltage		VF	$I_F = 1200 \text{ A,V}_{GE} = 0 \text{ V}$	_	3.6	_	V
Reverse recovery time		t _{rr}	$I_F = 1200 \text{ A,V}_{GG} = -15 \text{ V}$ di/dt = 1500 A/ μ s	-	-	-	μs
Thermal resistance	Transistor part	R _{th(j-f)}	Junction-fin(DC), Cooling on both sides	_	-	14.0	°C/kW
	Diode part	R _{th(j-f)}	Junction-fin(DC), Cooling on both sides	-	-	35.0	

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